

The Silicon Tracking System of the CBM experiment at FAIR

Anton Lymanets^{1,2} for the CBM collaboration

DPG Frühjahrstagung

14 - 18 March 2016

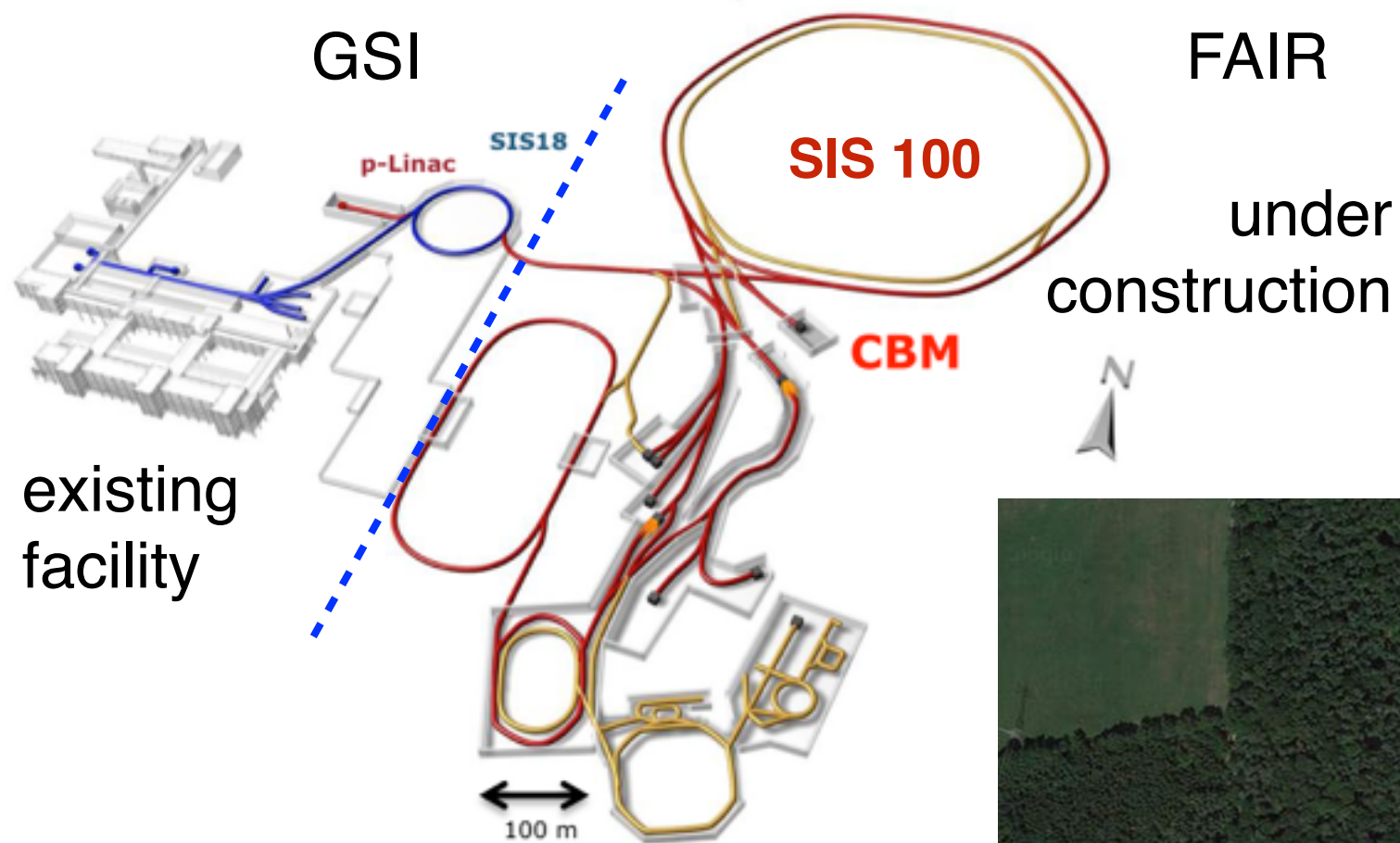
Technische Universität Darmstadt



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² Institute for Nuclear Research, National Academy of Sciences, Ukraine

Facility for Antiproton and Ion Research



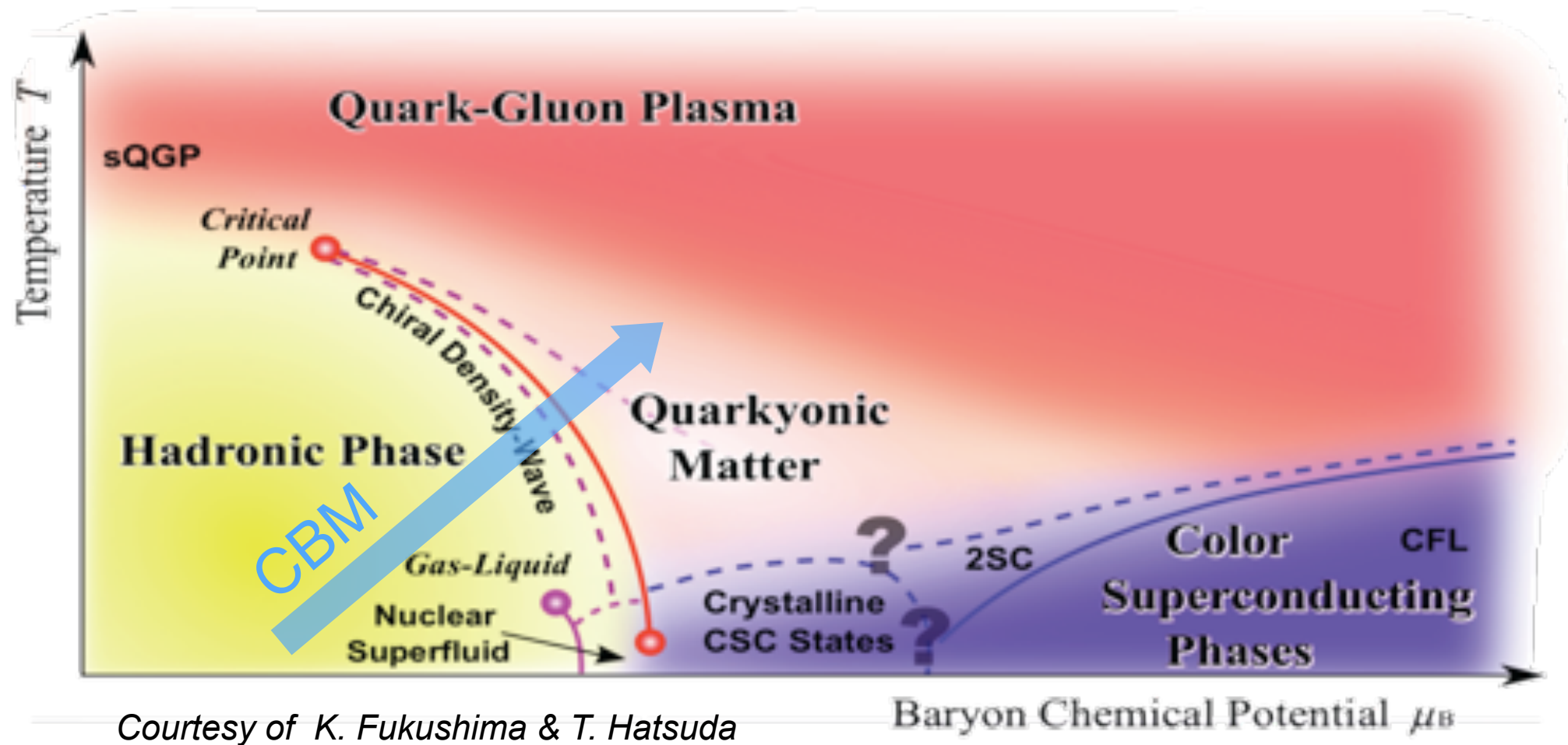
SIS-100

protons: 30 GeV

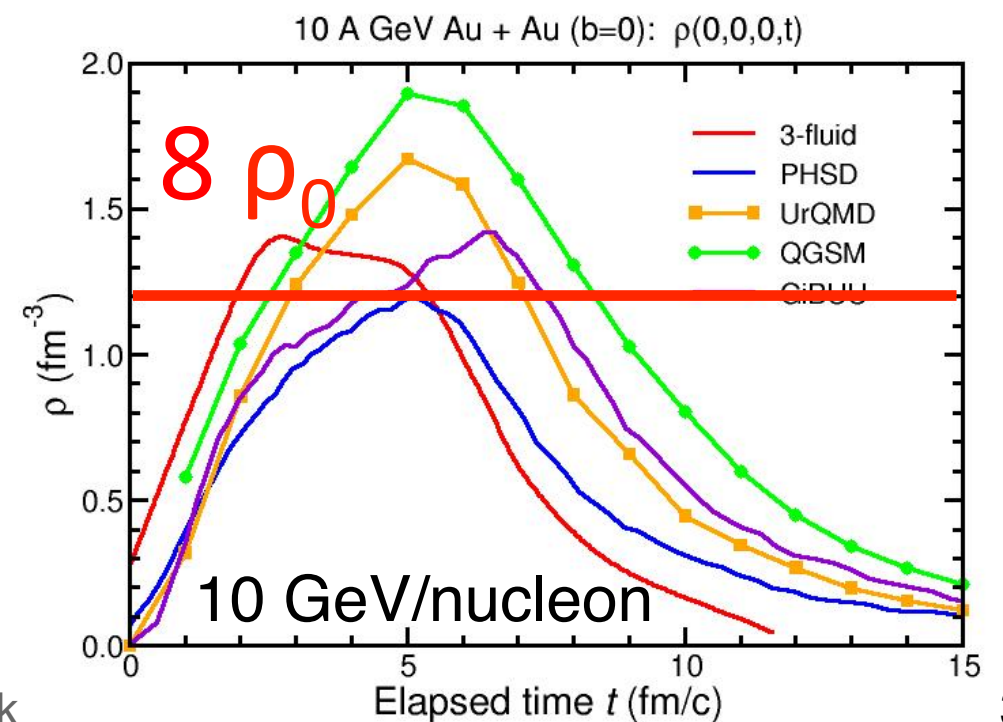
Au: 11 GeV/nucleon



QCD phase diagram

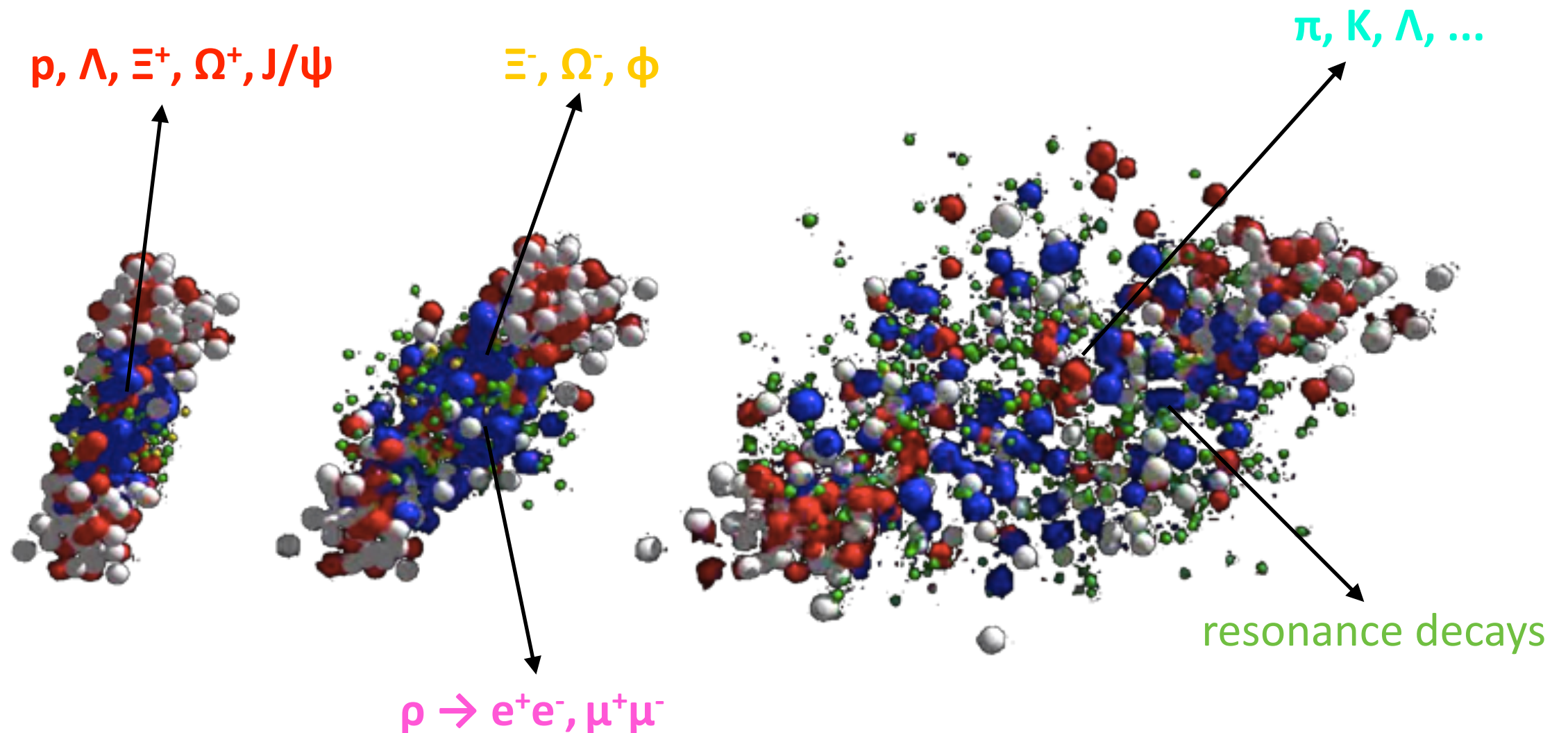


- nuclear matter formation at high baryon density and temperature
- models predict 1st order phase transition with formation of mixed and exotic phases
- existence of critical end-point



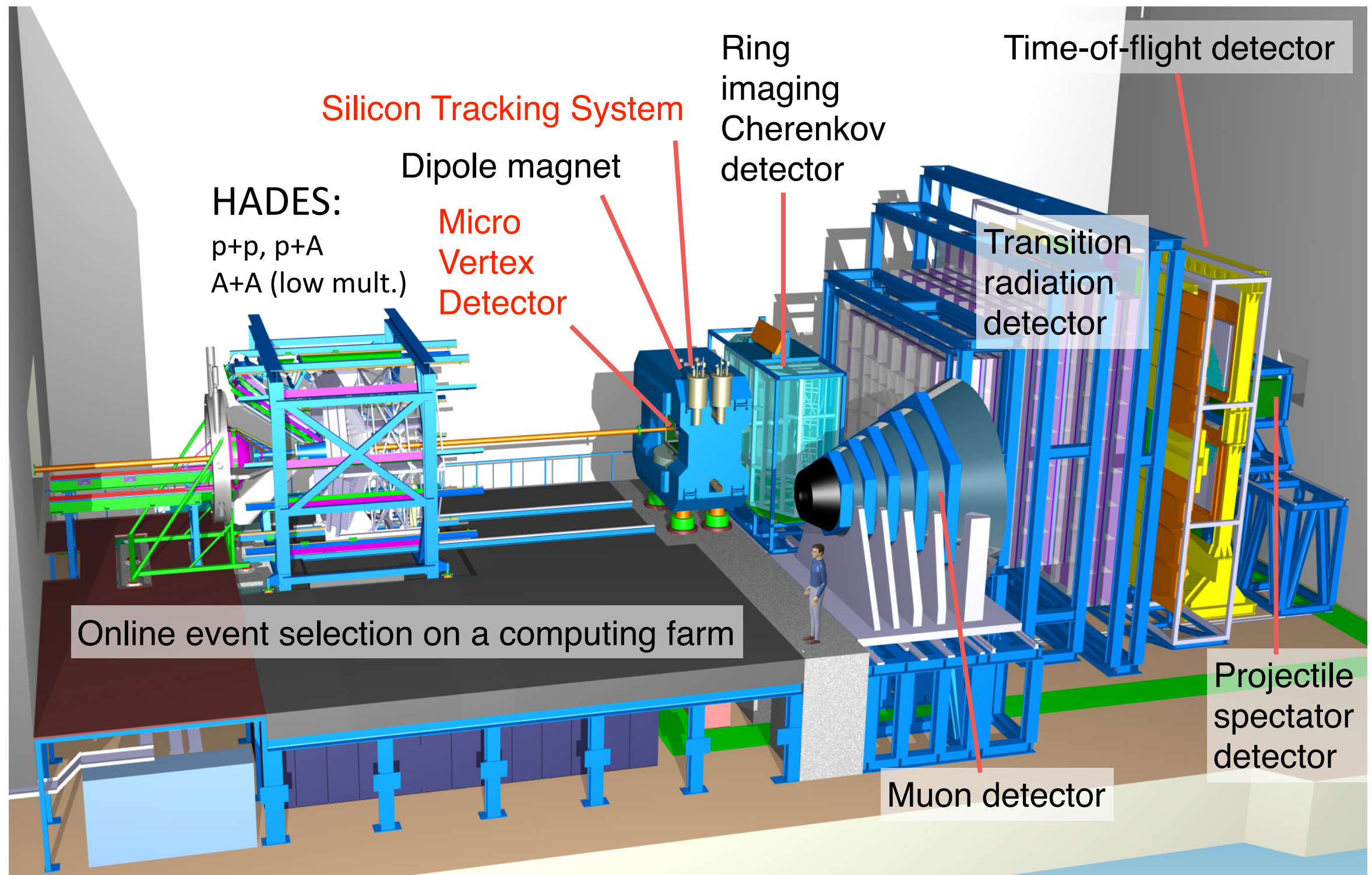
Probing the dense fireball

Au+Au collision at 10.7 GeV/nucleon as simulated in the UrQMD transport code



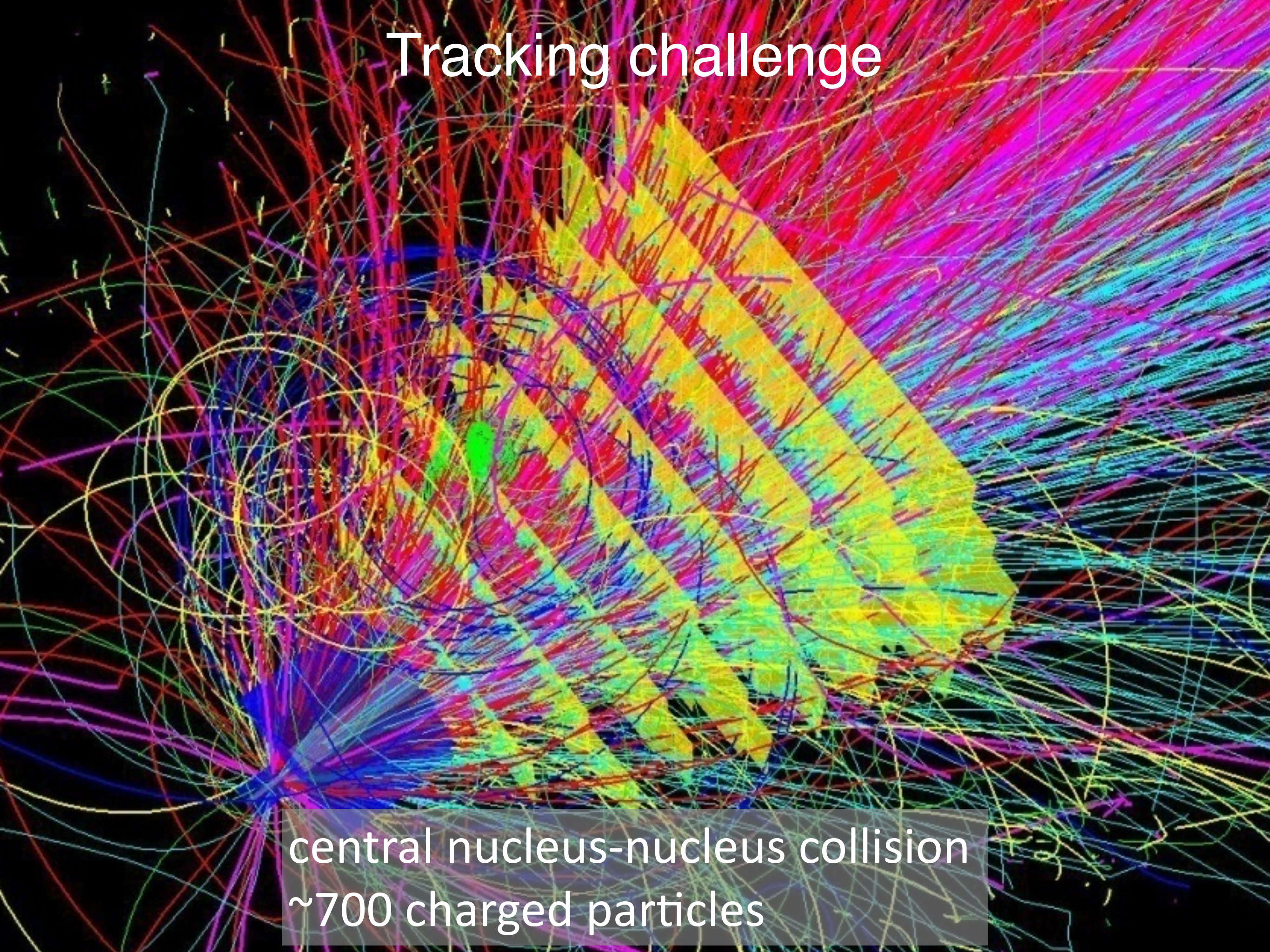
- Leptonic and hadronic signals from all stages of nucleus-nucleus collisions
- Rare probes: multistrange hyperons, low mass vector mesons, charmonium, strange dibaryons, hypernuclei.

CBM experiment



- Vertexing: MVD
- Tracking: STS, MUCH, TRD, ToF
- Particle ID: RICH, TRD, ToF
- Calorimetry: ECAL, PSD

Tracking challenge

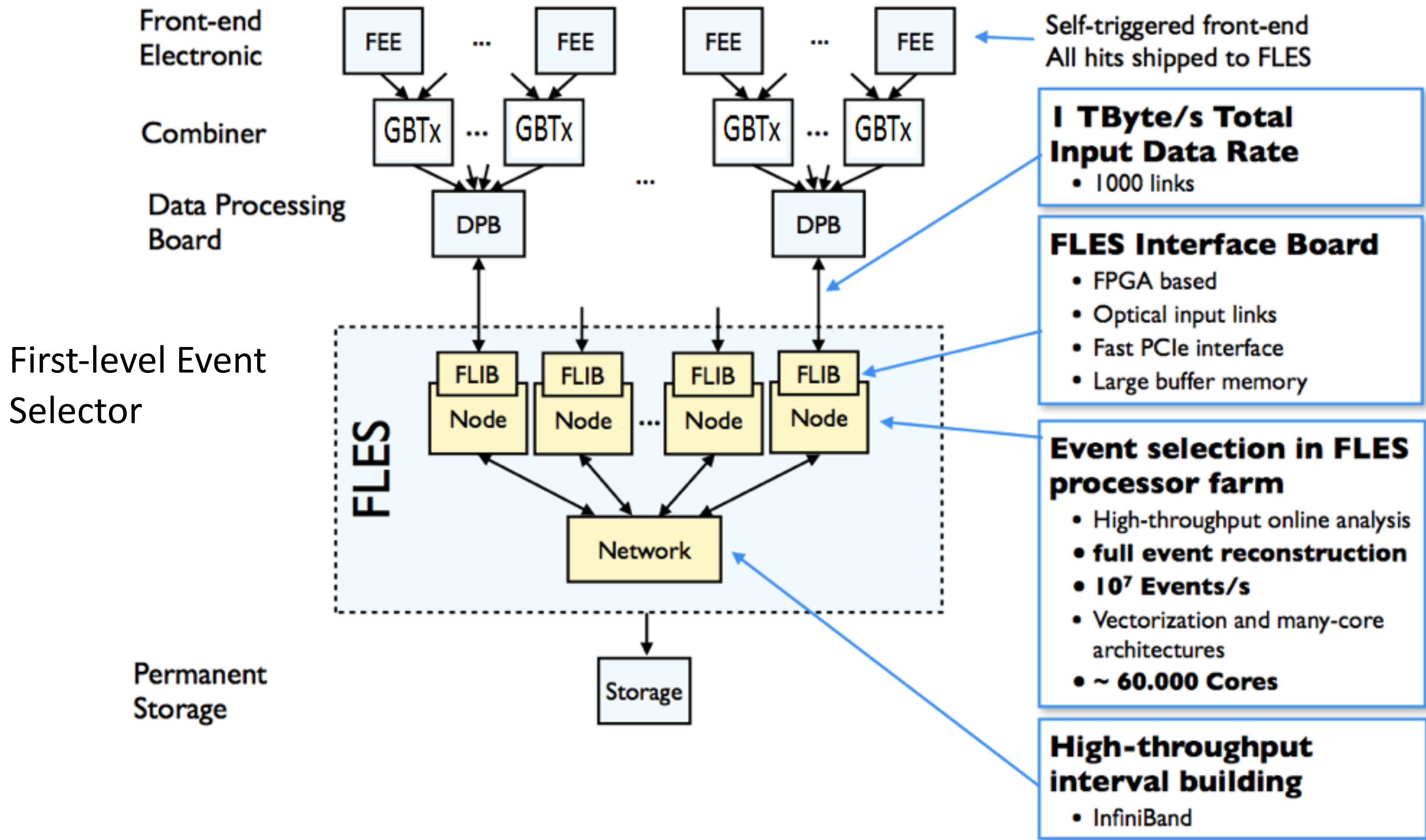


central nucleus-nucleus collision
~700 charged particles

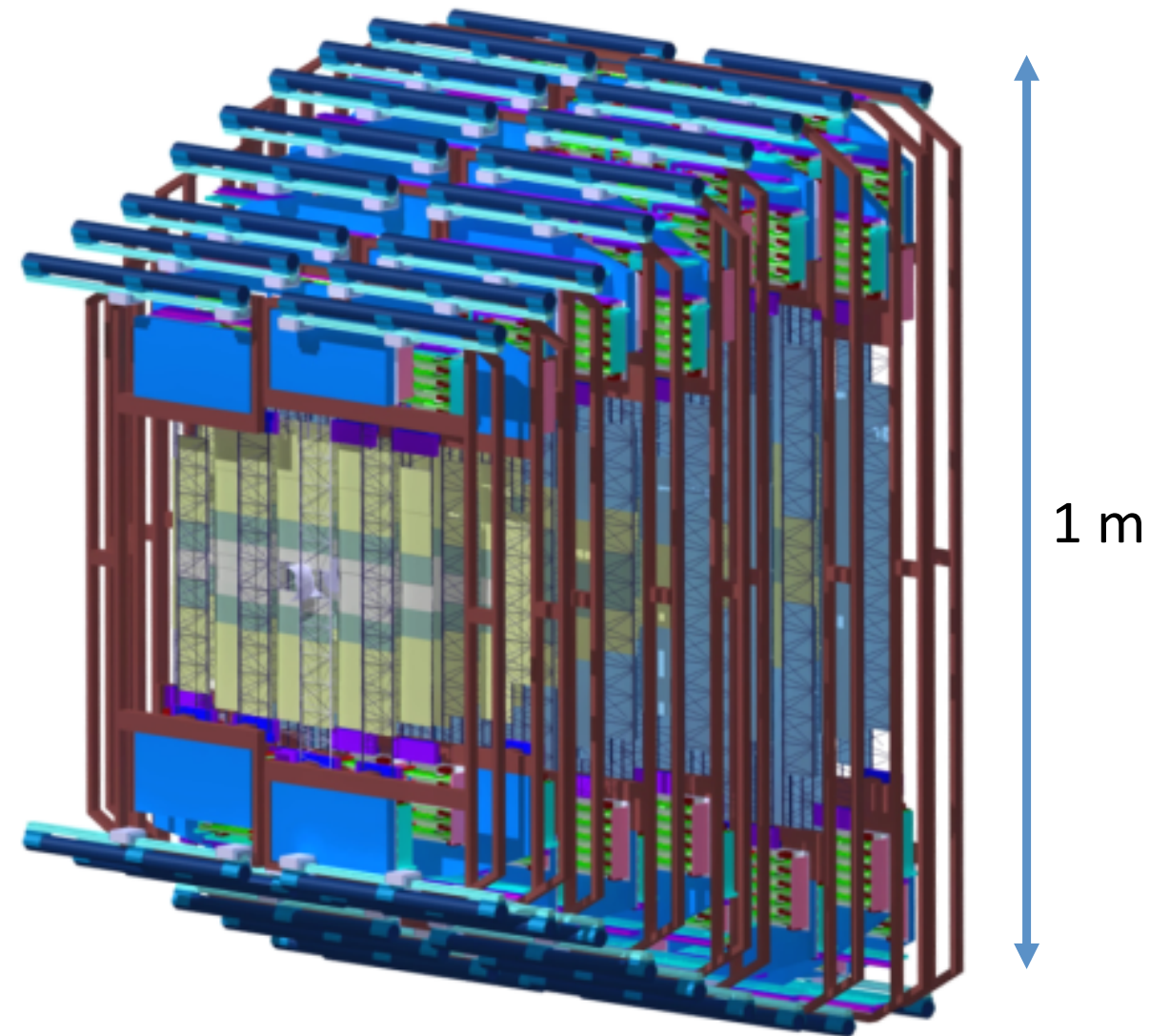
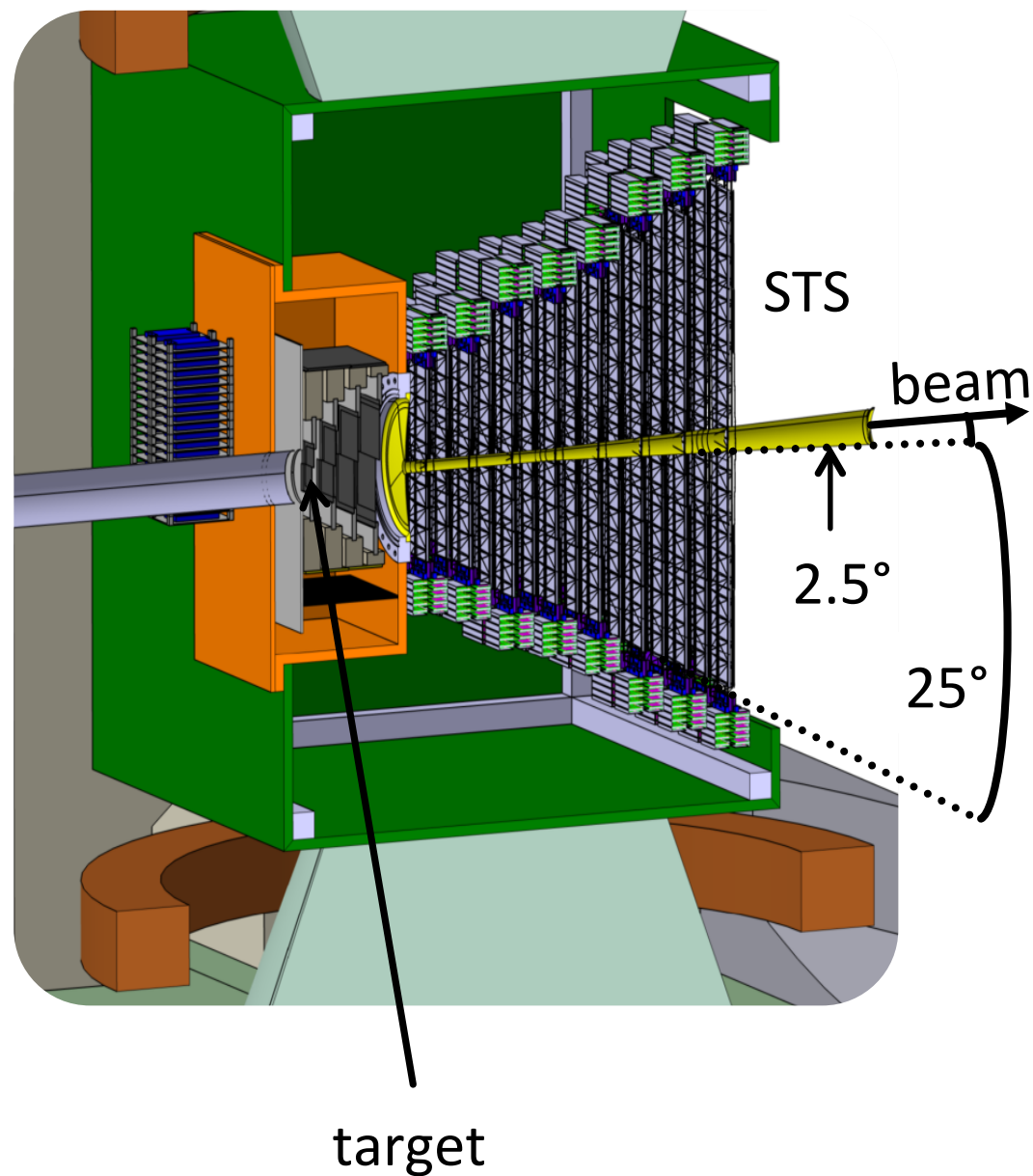
Experimental requirements

- $10^5 - 10^7$ Au+Au collisions per second.
- secondary vertex determination ($\sigma \approx 50 \mu\text{m}$)
- track reconstruction from hadron and lepton probes
- fast and radiation tolerant detectors
- self-triggering front-end electronics
- fast data acquisition system + online event selection
on a computing farm
- 4D track reconstruction

Online data flow



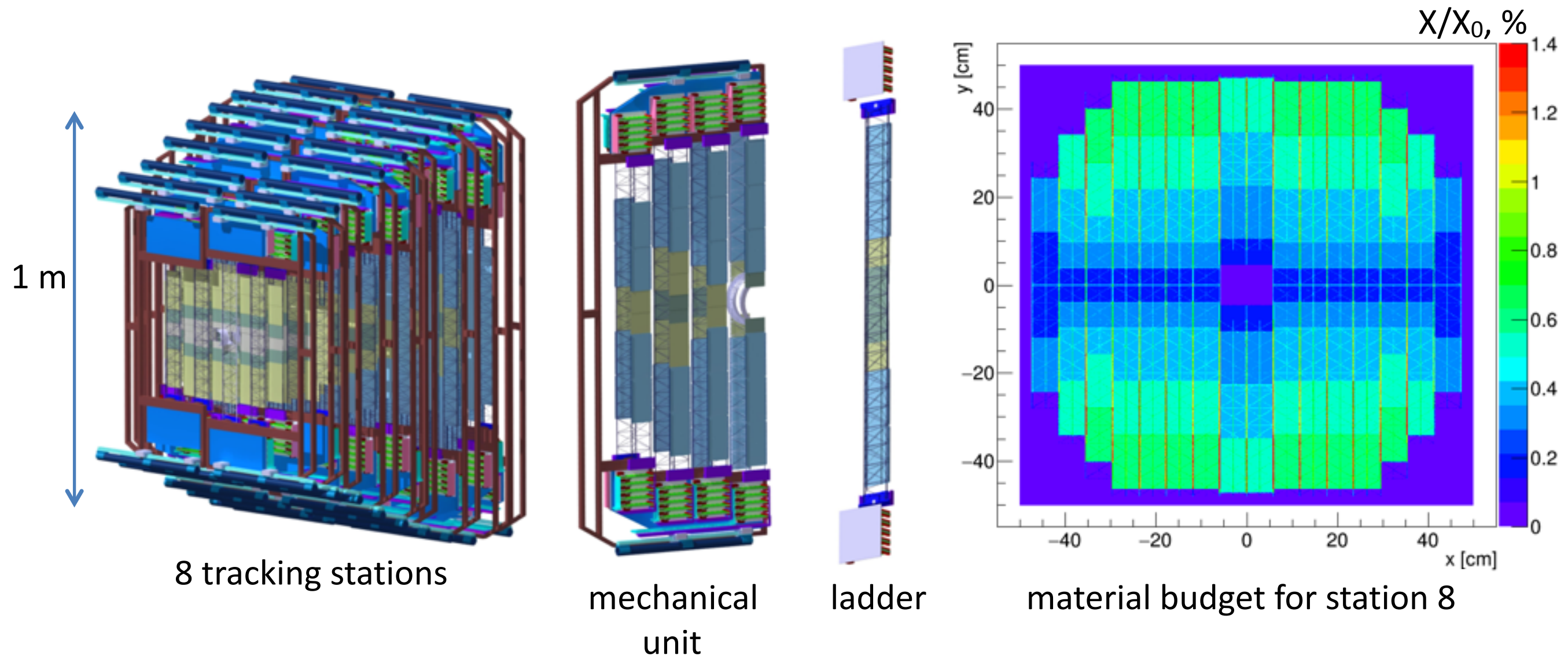
Silicon Tracking System



- 8 tracking stations in the magnet aperture
- double-sided silicon microstrip detectors

- Acceptance: $2.5^\circ < \theta < 25^\circ$
- Active area: 4 m^2

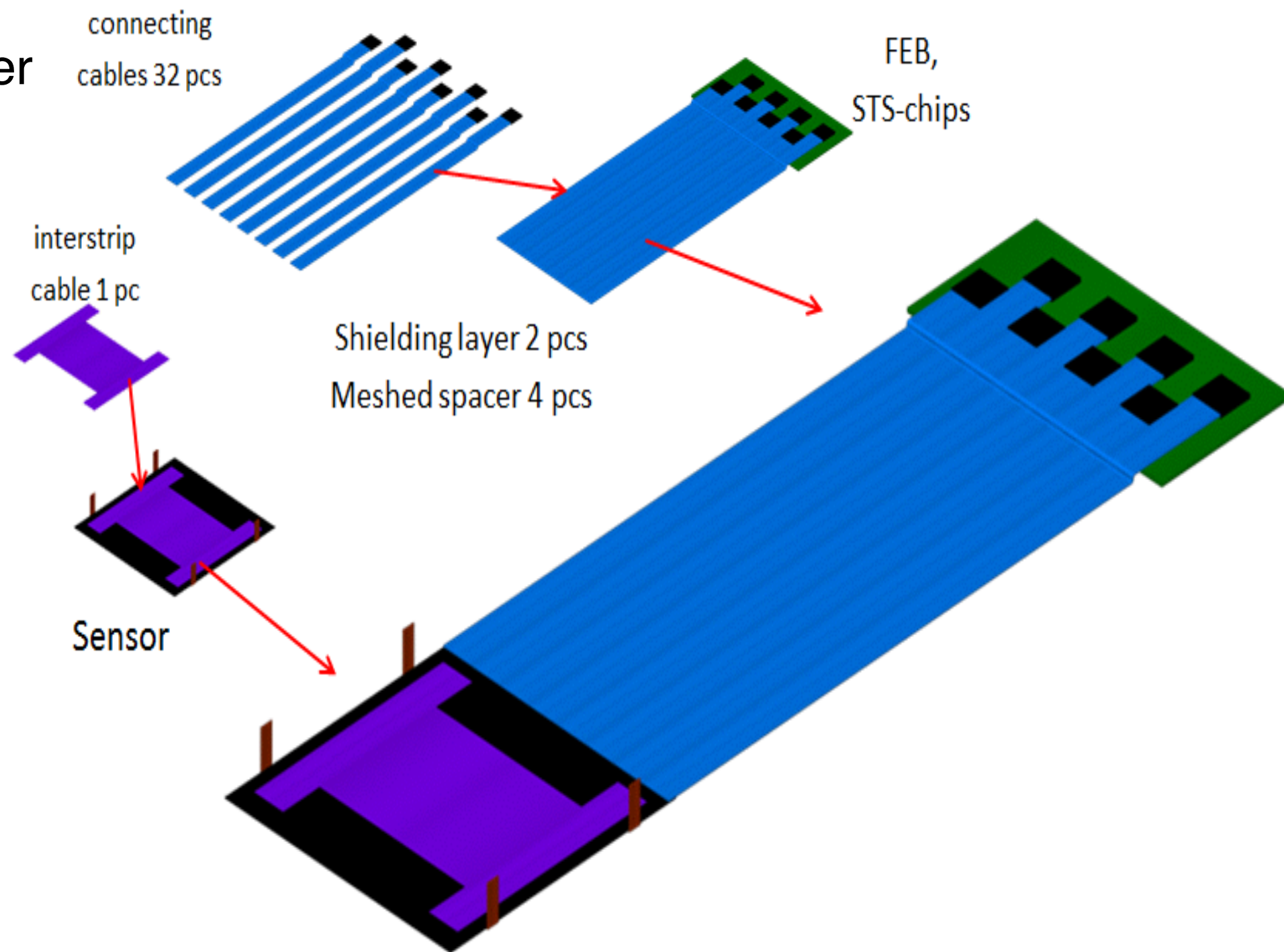
STS integration concept



896 detector modules including:
1220 double-sided microstrip sensors
~ 1.8M readout channels
~ 16 000 readout chips
~ 16 000 ultra-thin readout cable stacks

Detector module concept

896 modules required
4-5 modules per ladder

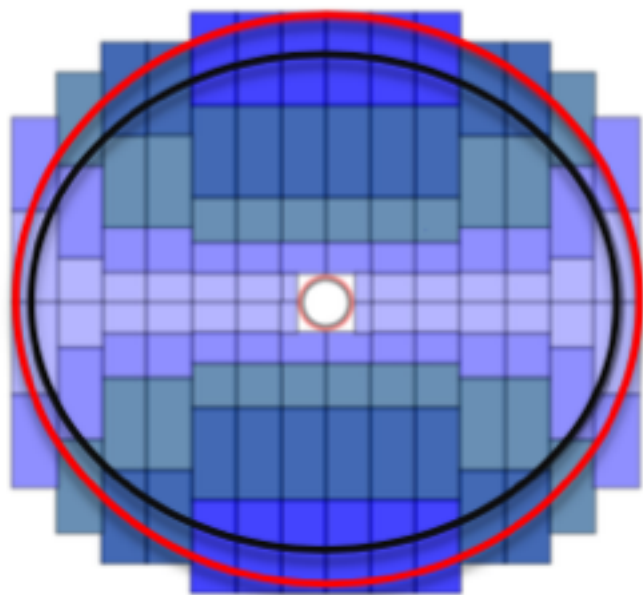


Modules comprises:

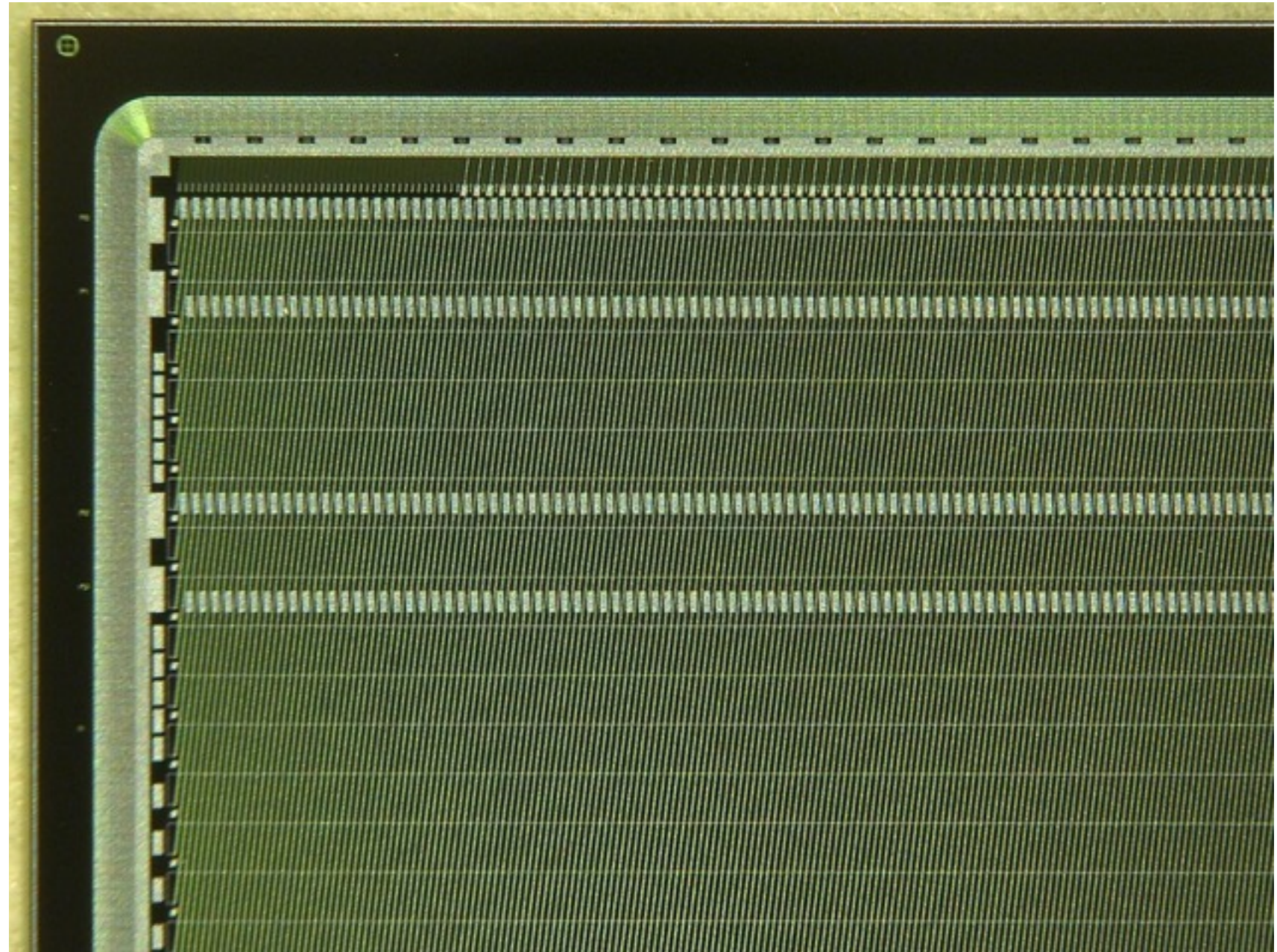
- sensor
- ultra-thin microcables
- front-end board

Silicon microstrip sensors

- double-sided
- 1024 channels per side
- $58\ \mu\text{m}$ pitch
- $300\ \mu\text{m}$ thick
- stereo angle 7.5° (p-side)
- dimensions:
 $6\times 2\ \text{cm}^2$, $6\times 4\ \text{cm}^2$,
 $6\times 6\ \text{cm}^2$, $6\times 12\ \text{cm}^2$
- 2nd metallization to
interconnect short
corner strips



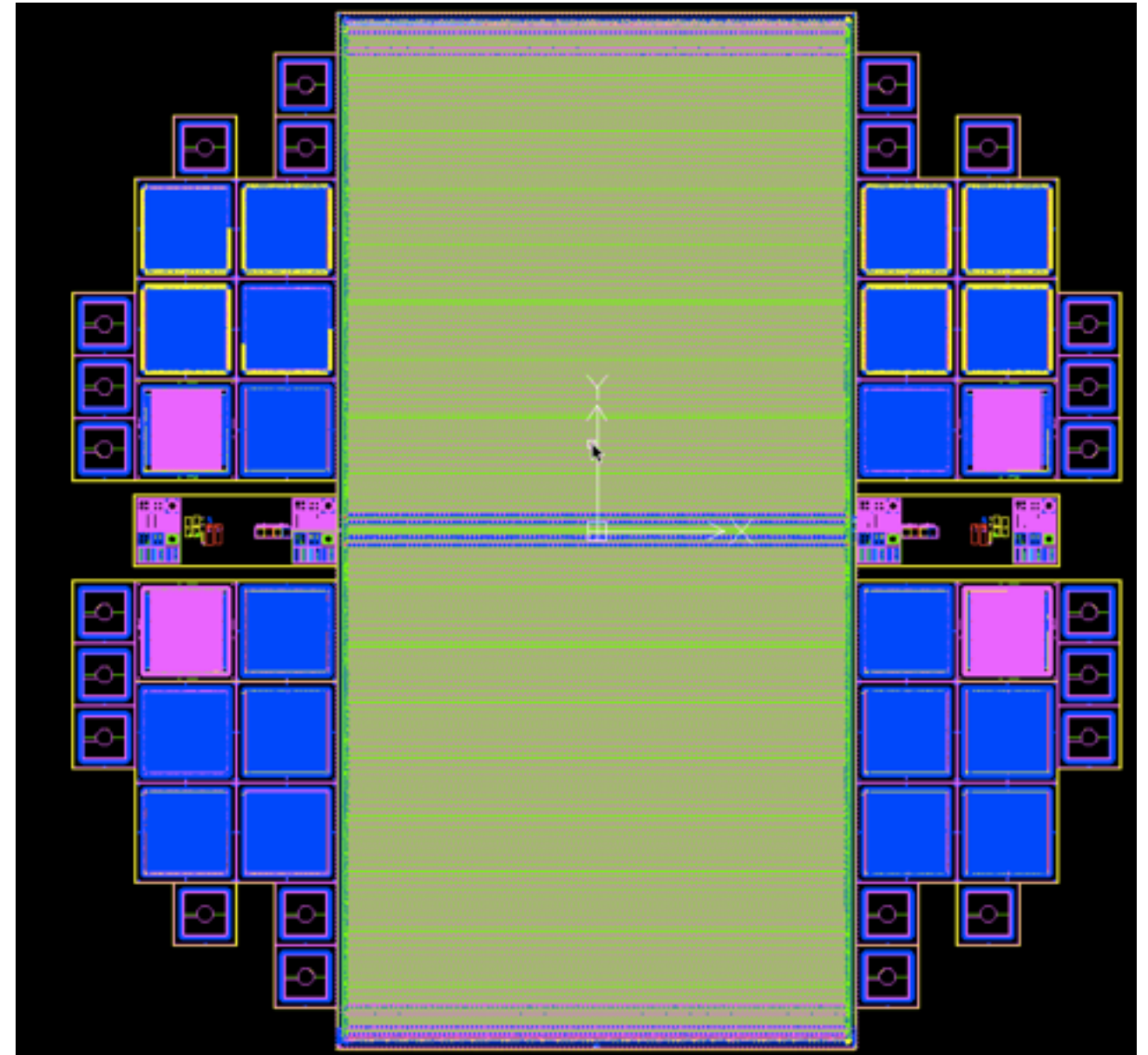
Layout
STS5 and 6



Silicon microstrip sensors

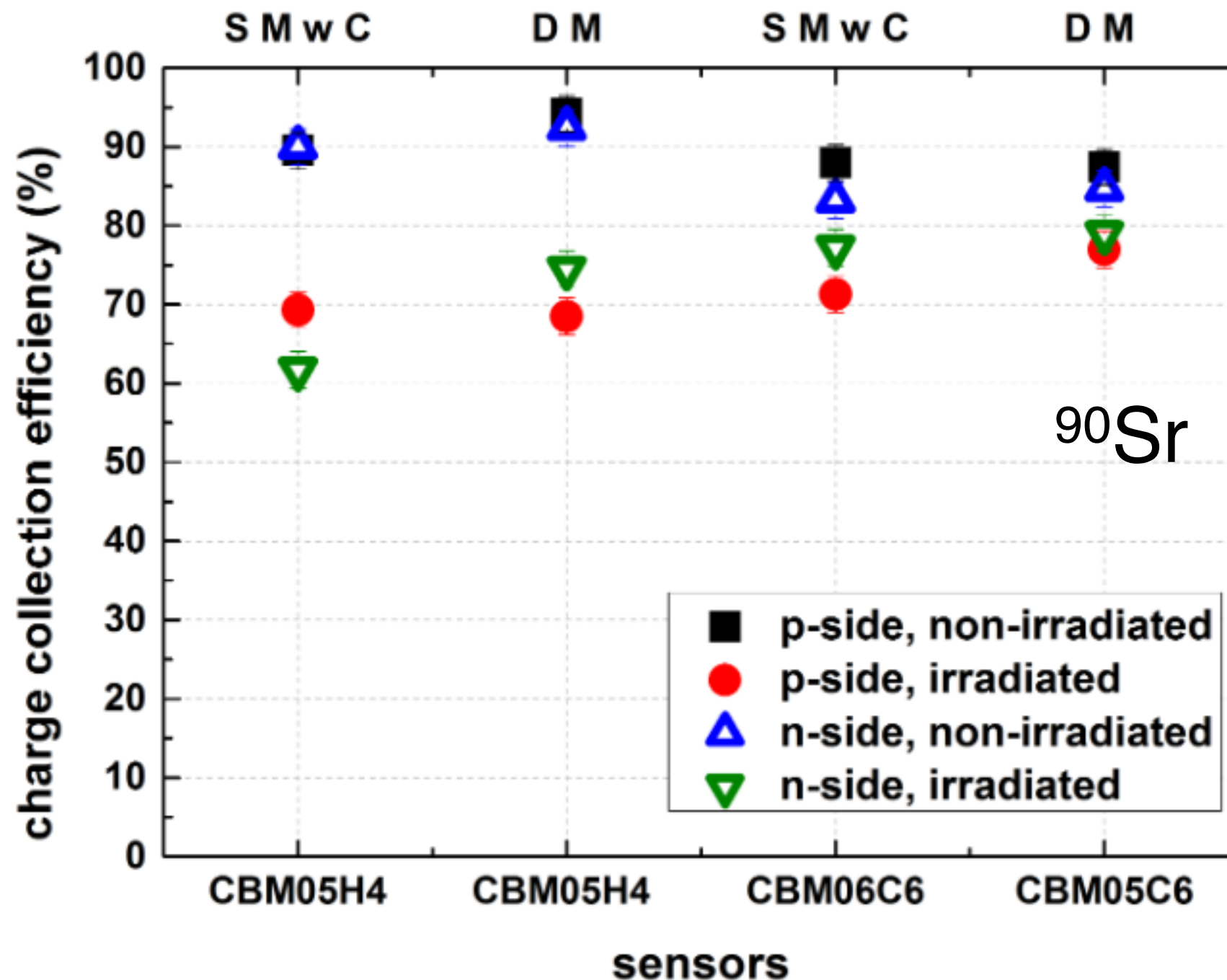


two daisy-chained sensors
with $6 \times 6 \text{ cm}^2$ size each



$6 \times 12 \text{ cm}^2$ sensor design with readout
pads in the middle of the sensor (in
production by Hamamatsu)

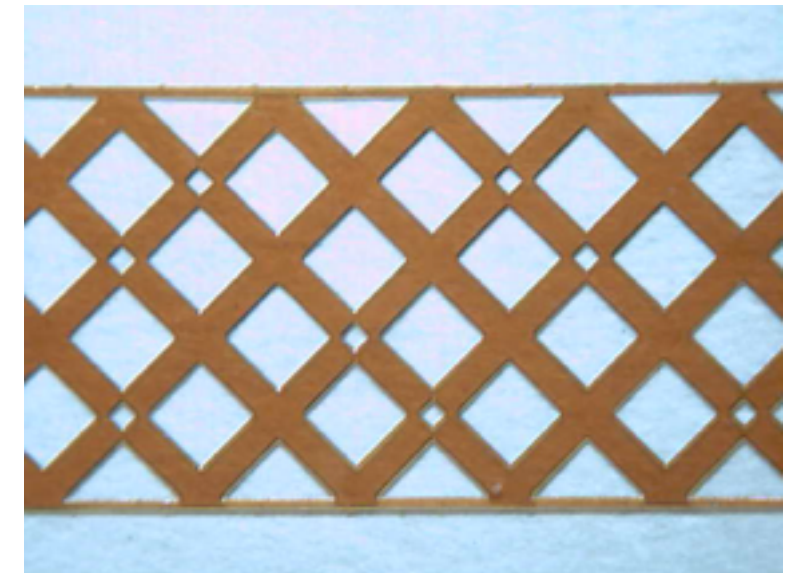
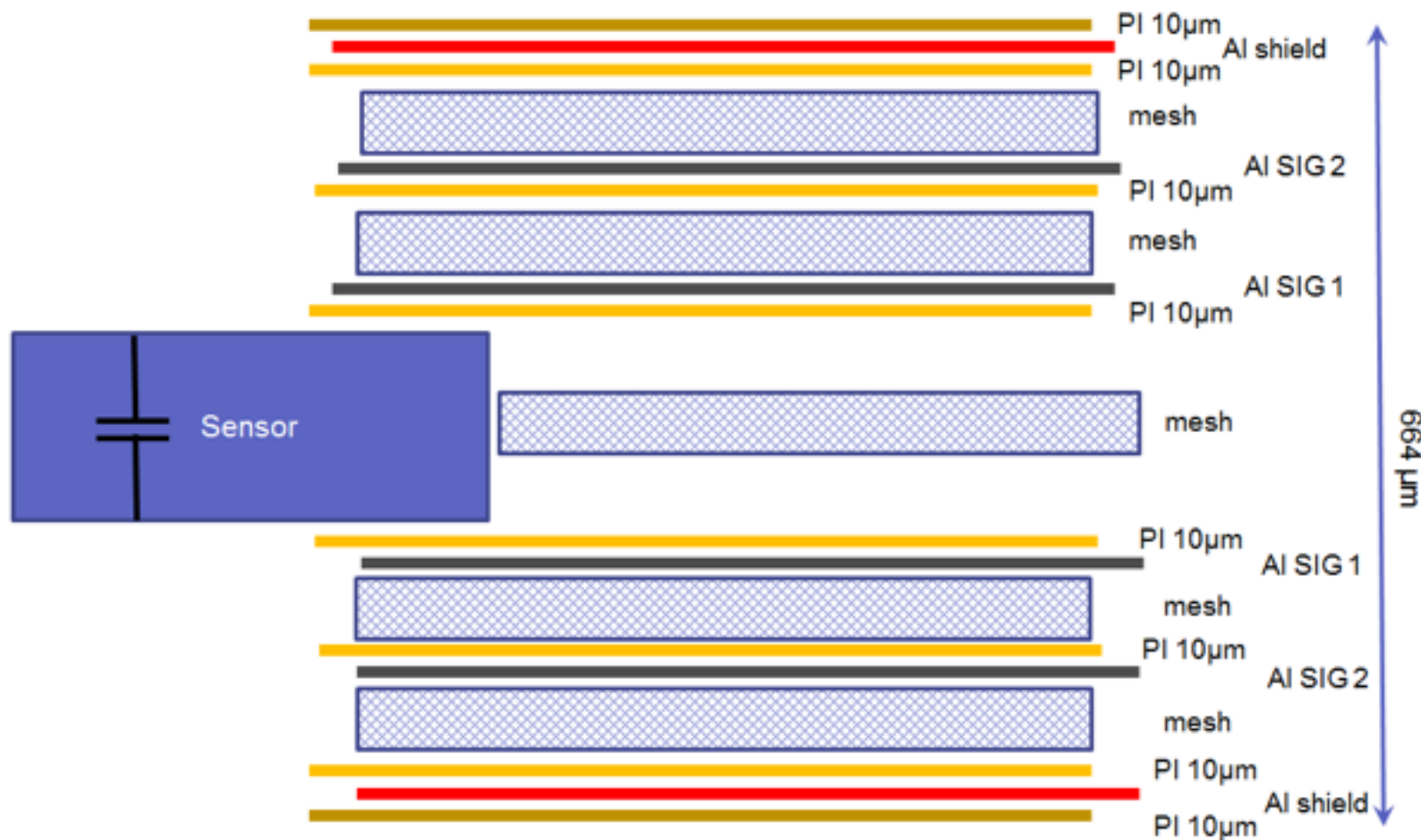
Charge collection studies



Irradiated sensors:
 $\Phi = 2e14 \text{ n}_{eq}/\text{cm}^2$
 (twice maximum
 fluence for CBM
 lifetime)

- Irradiated sensors show reduction in charge collection efficiency of up to 20%
- CCE confirmed in a 2 GeV proton beam test at COSY

Microcables



meshed spacer

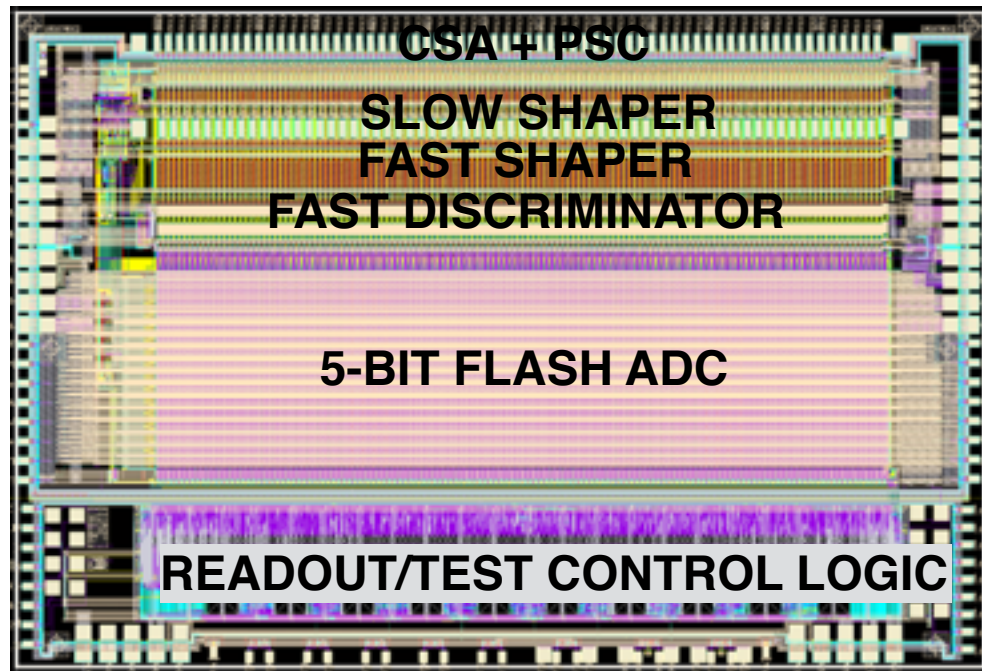
signal layer: 64 Al lines of 116 μ m pitch, 10 μ m thick on 14 μ m polyimide, lengths up to 55 cm



Material budget per cable stack: 0.228 X_0 (equivalent to 213 μ m Si)

STS-XYTER ASIC

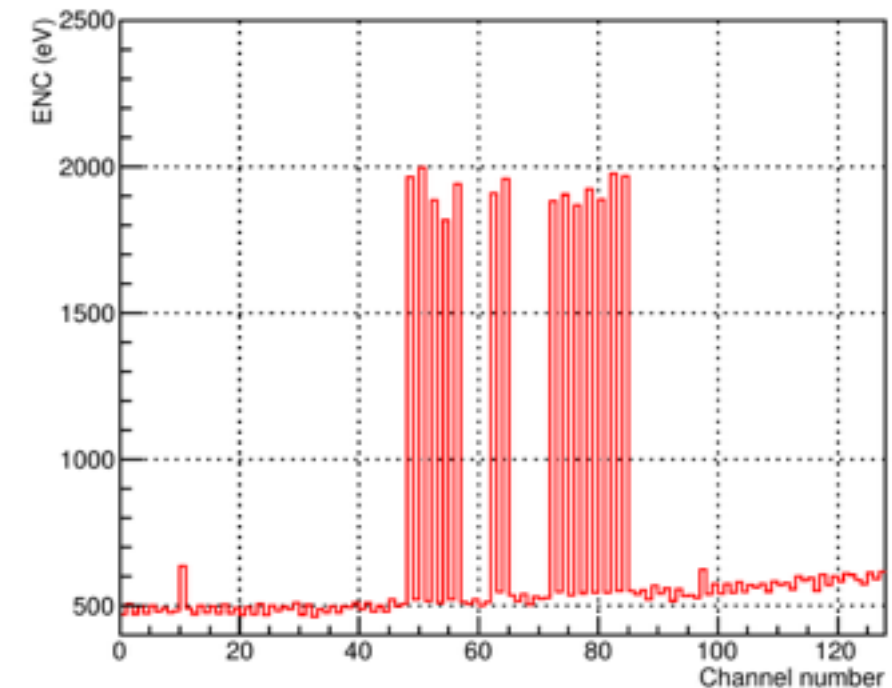
STS-XYTER ASIC



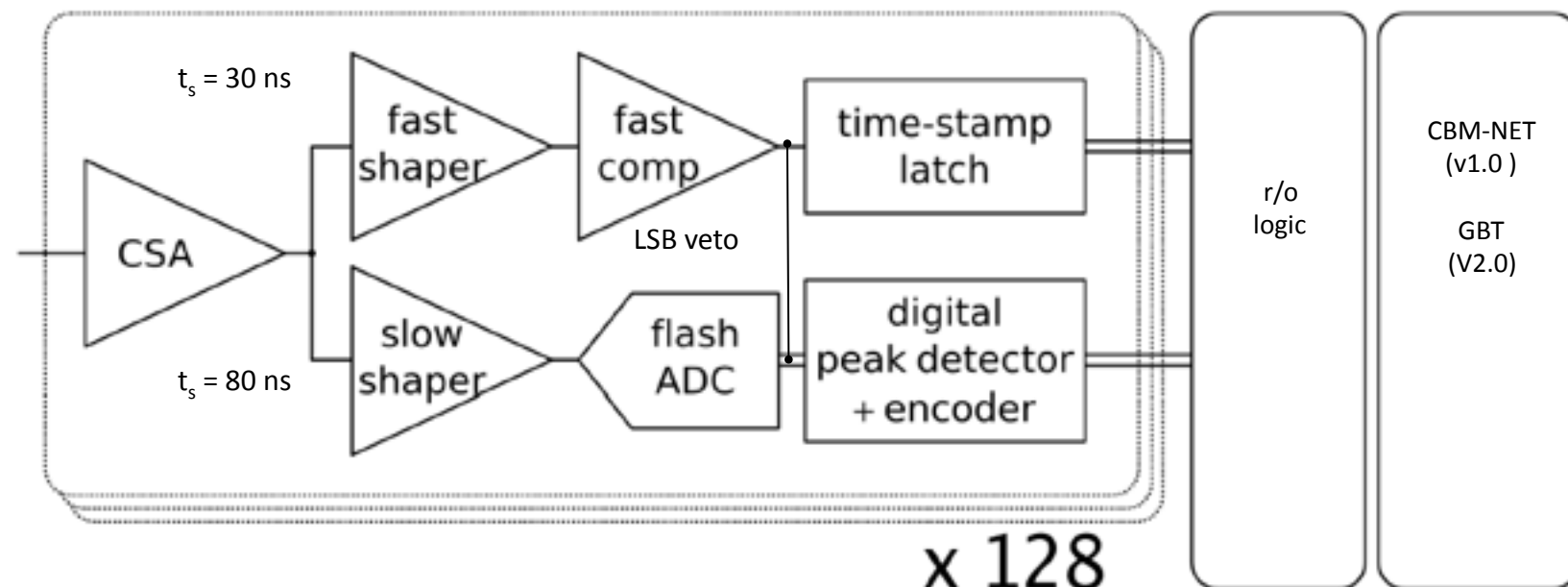
channels	128, polarity +/-
noise	1000 e ⁻ at 30 pF load
ADC range	16 fC, 5 bit
clock	160 MHz
power	< 10 mW/channel
timestamp	< 5 ns resolution
out interface	(1..5)×320 Mbit/s LVDS

- data driven architecture
- fast branch: time-stamp
- slow branch: signal digitization
- double-threshold discrimination: time stamp is vetoed if ADC produced no signal

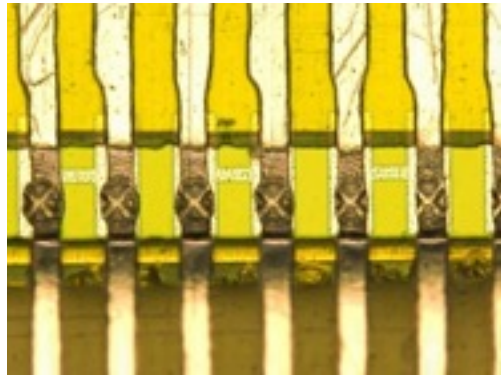
ENC vs channel number



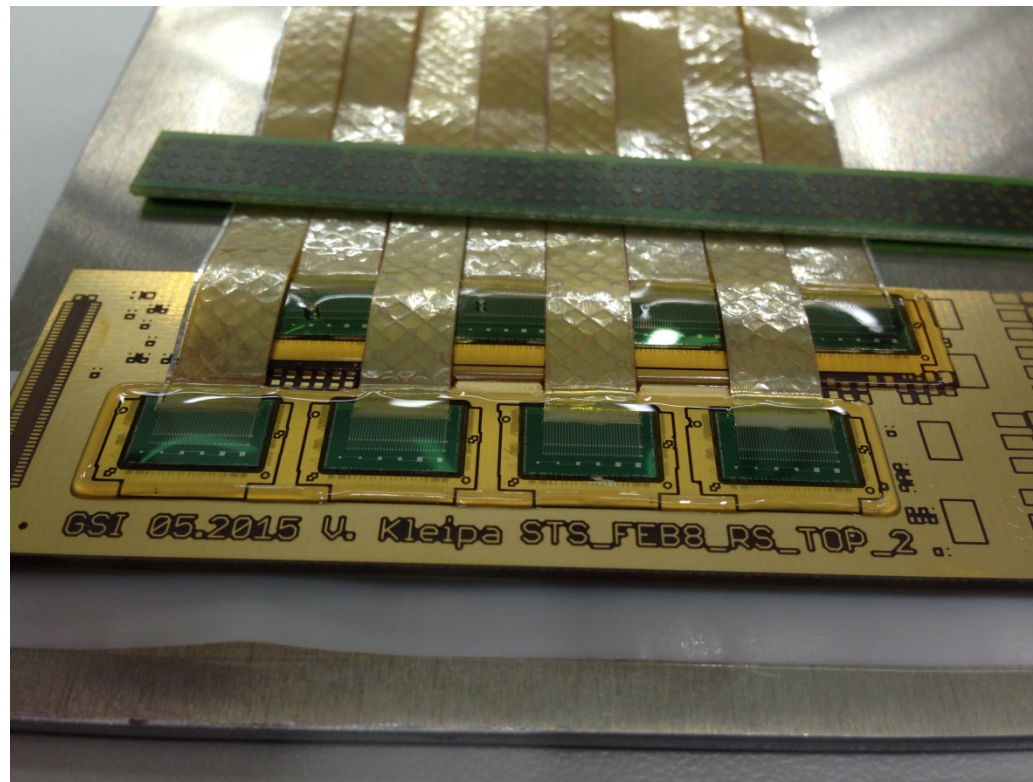
- Noise performance with STS-XYTER v1 is ~1800 e⁻ (chip + two daisy-chained sensors with 62 mm strips + 30 cm cable)
- Significant improvements expected after redesign



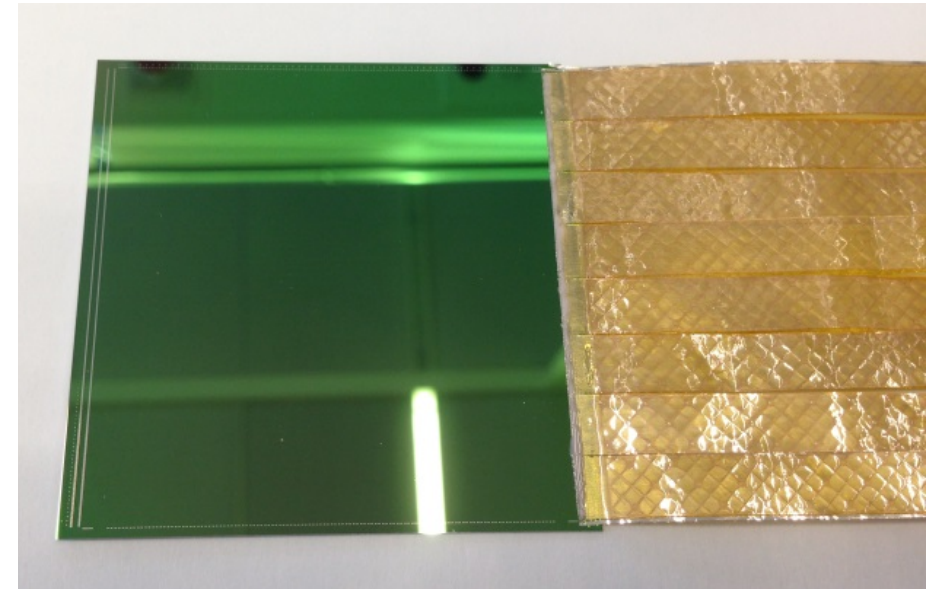
Detector module assembly



1. TAB bonding of microcables to ASICs



2. Wire bonding ASICs to front-end boards + bond protection (glob top)



3. TAB bonding of microcables to sensors on both sides



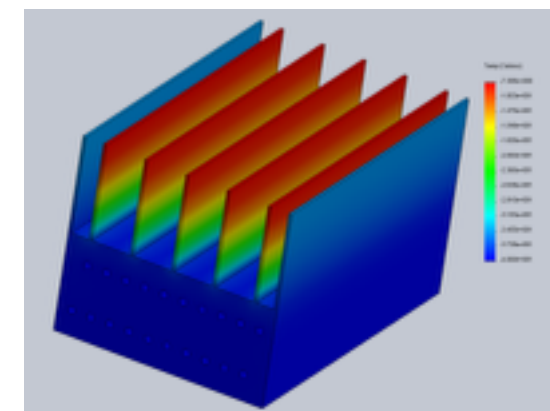
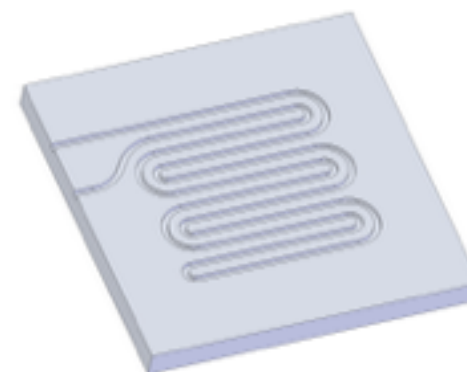
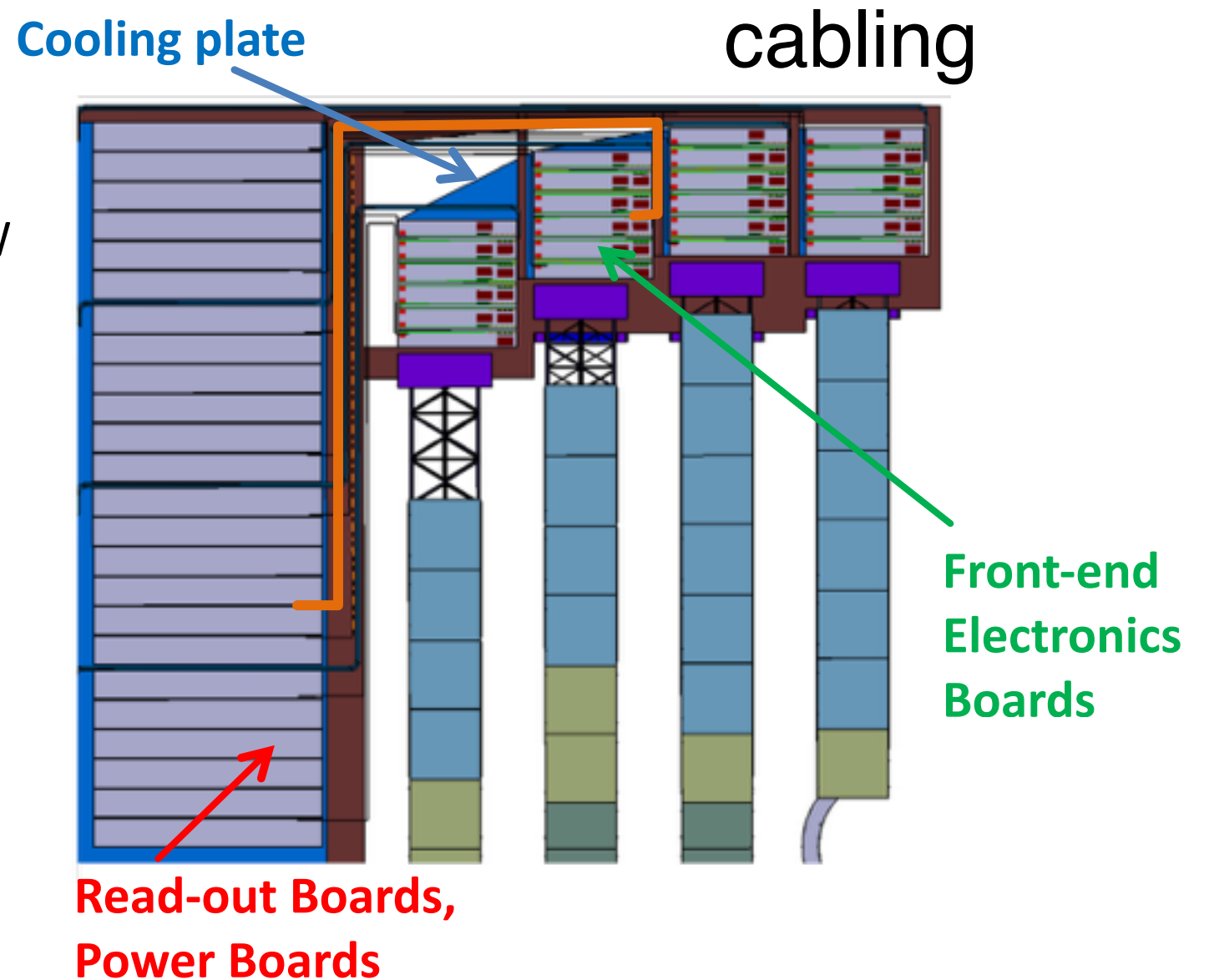
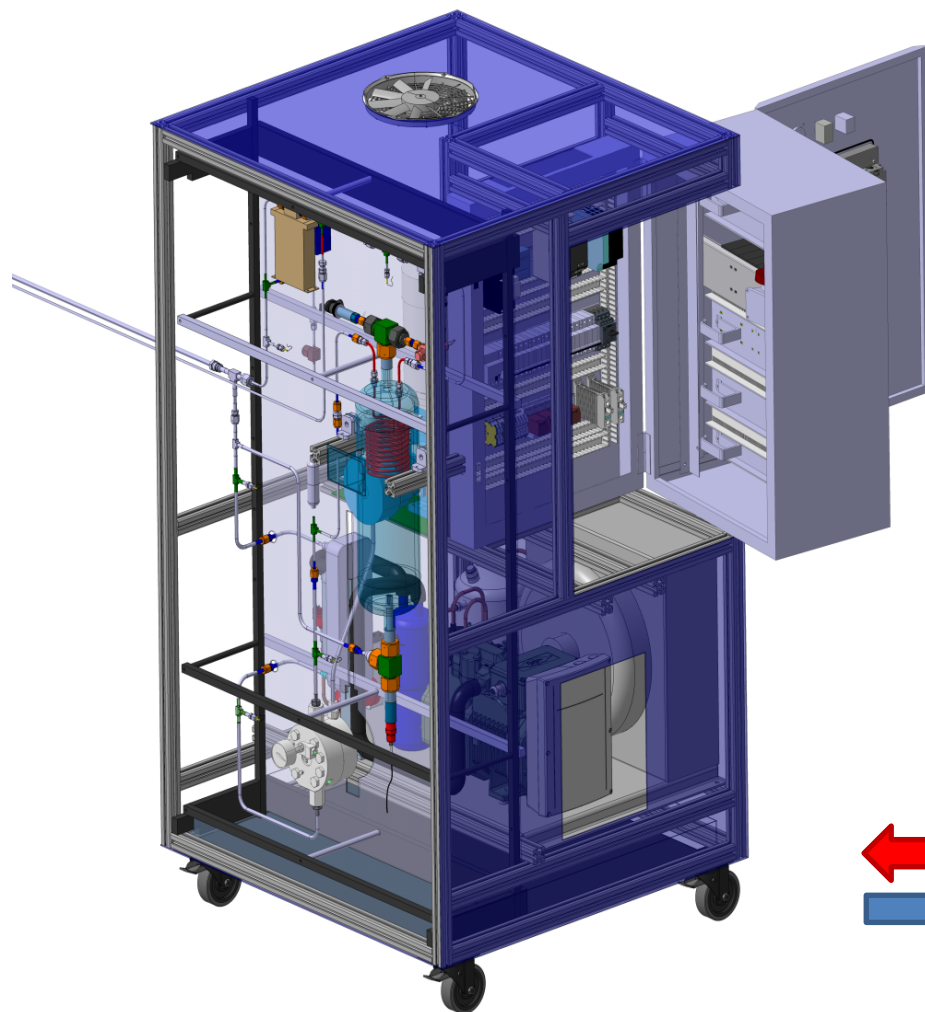
Current engineering studies

cooling

Bi-phase CO₂ cooling system

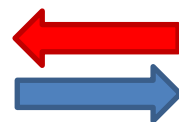
STS electronics total power dissipation: 42 kW

TRACI XL: 1 kW cooling prototype

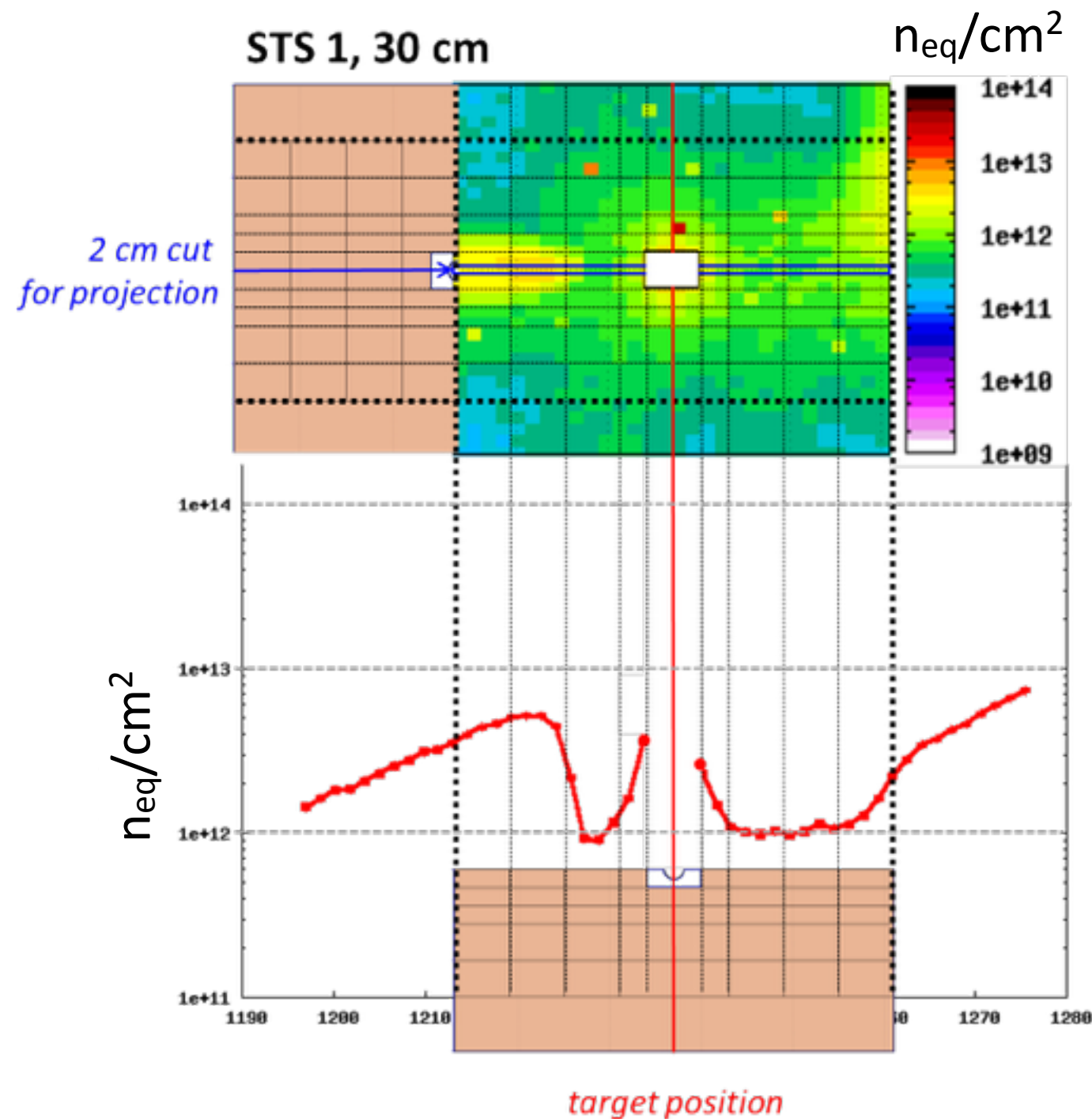


FEB stack
200 W

cooling plate with integrated channels



Radiation environment



Radiation load per typical operation year

- Non-ionizing dose: $10^{13} n_{eq}/cm^2$ (worst case)
- Ionizing dose: <100 kRad

Operation conditions:

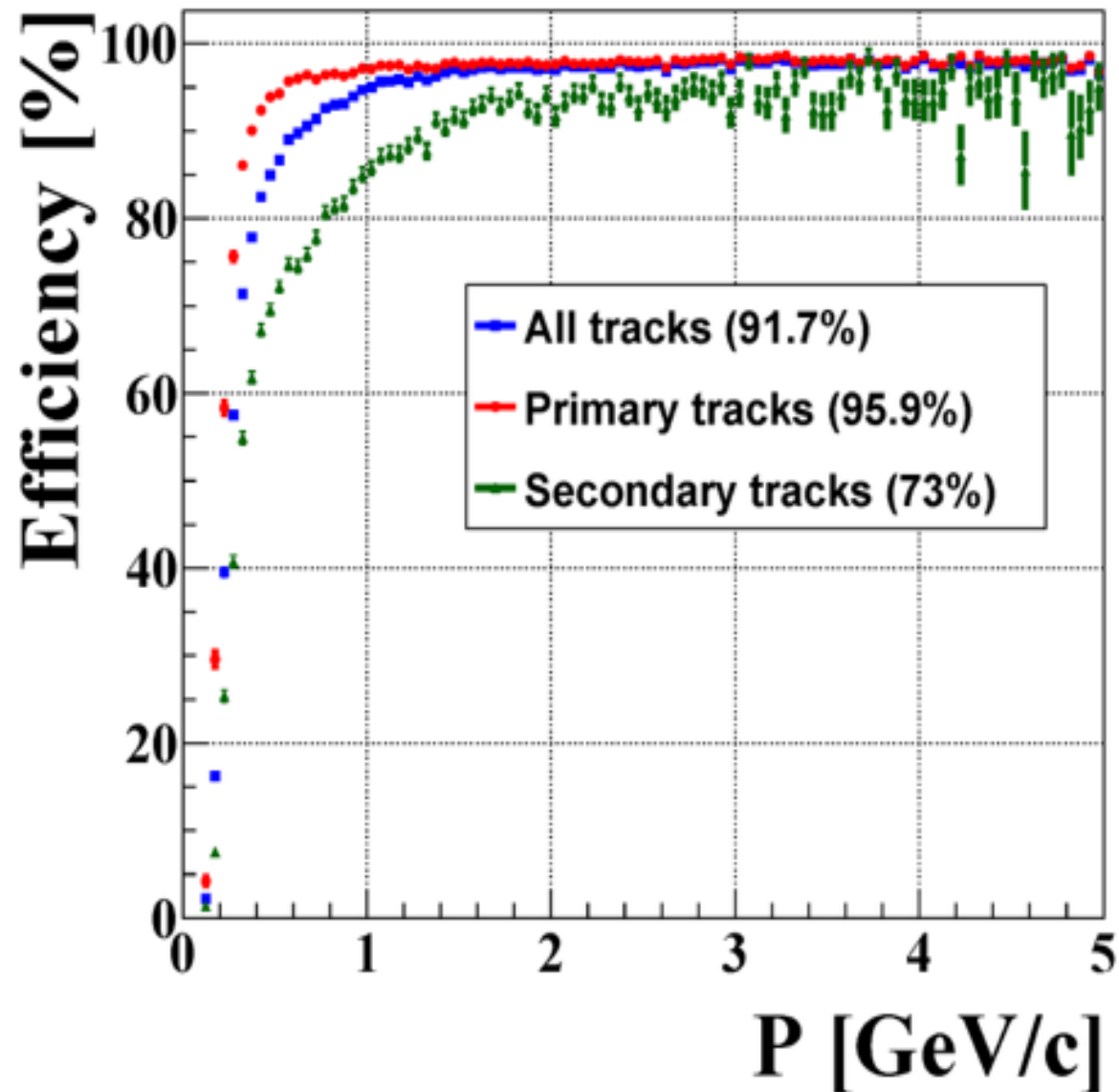
1 month of running at 10^9 ions/s on a 1% X_0 target

FLUKA calculation of non-ionizing dose for 10 AGeV

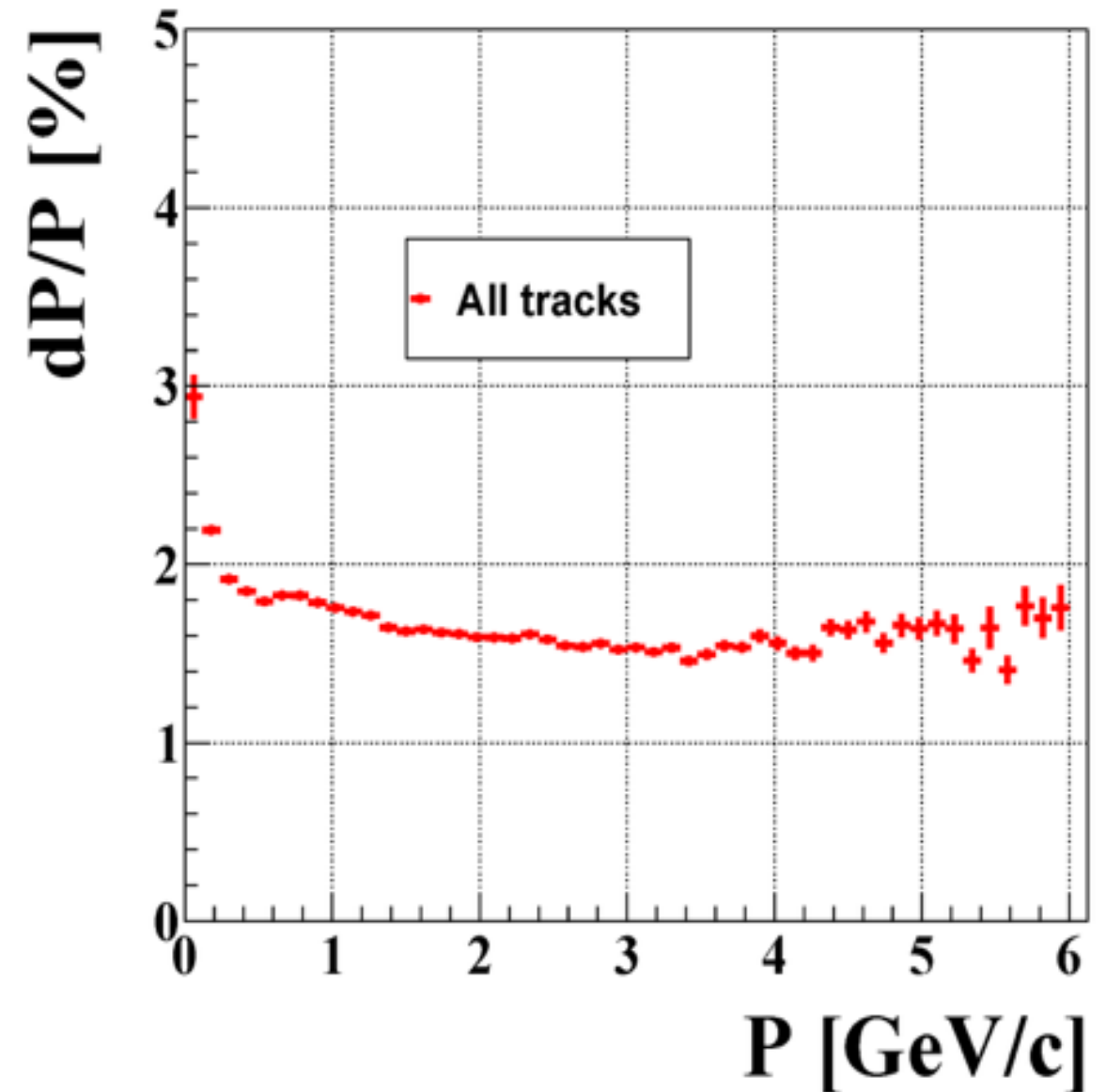
Au+Au collisions at SIS100 and the CBM experiment in electron-hadron configuration.

STS performance simulation

Track reconstruction efficiency



Momentum resolution



- realistic detector model
- CbmRoot simulation framework

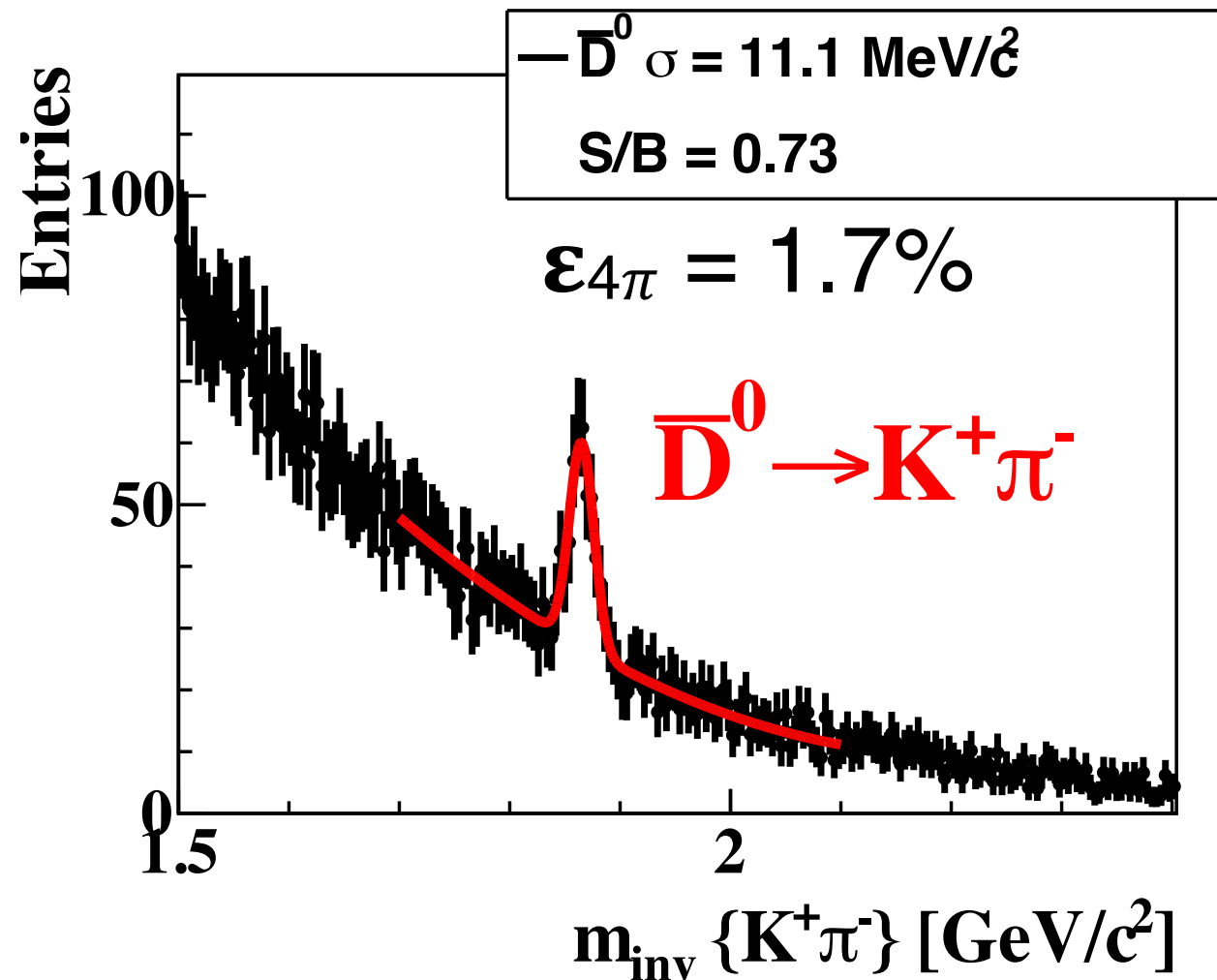
- Cellular Automaton track finder
- Kalman Filter track fitting

Feasibility studies at SIS-100

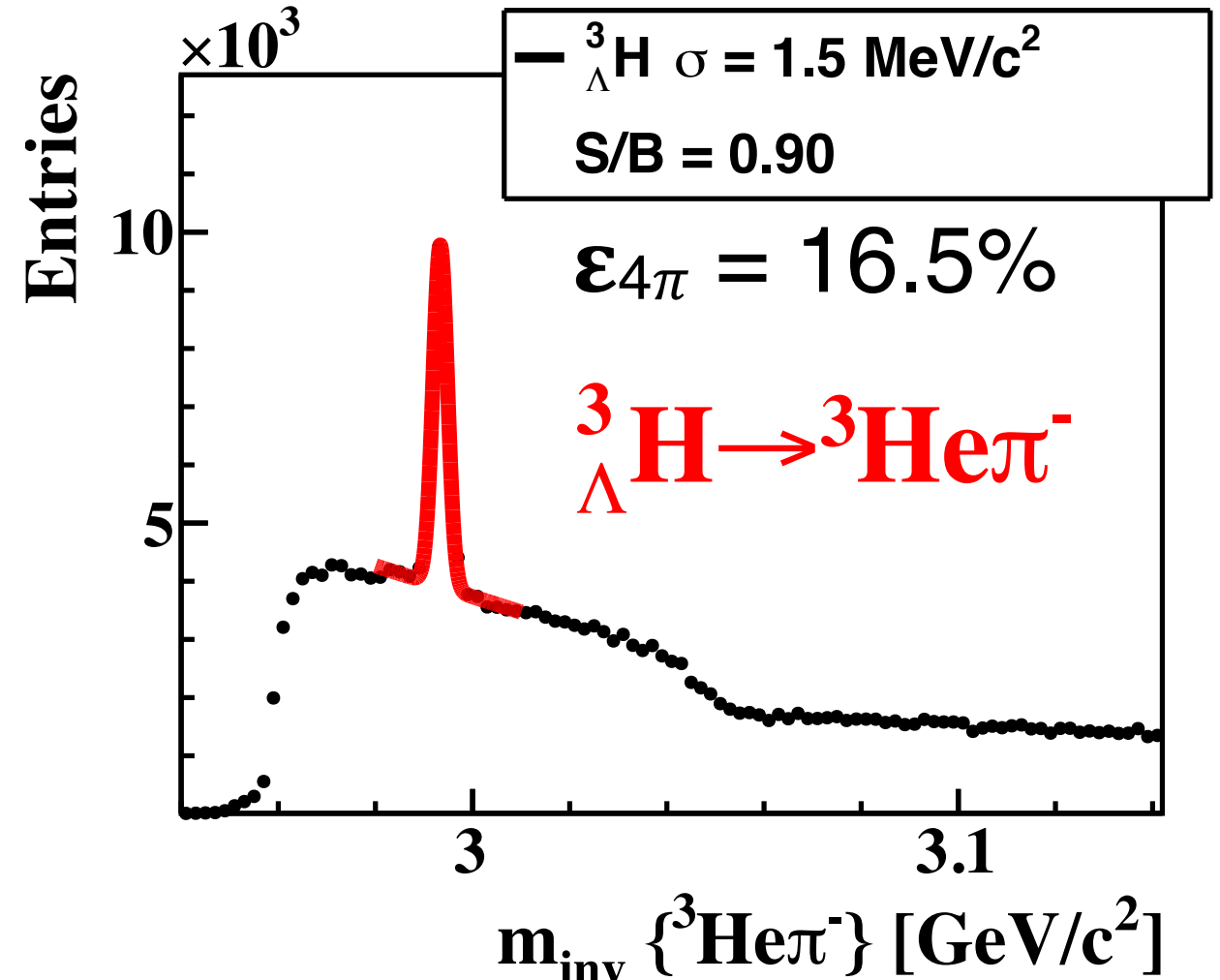
Operation scenario:

from pA (up to 30 GeV) to AuAu (2–11 GeV/nucleon) systems

Tue, 17:45 HK 25.5
Tue, 16:30 HK 24.1



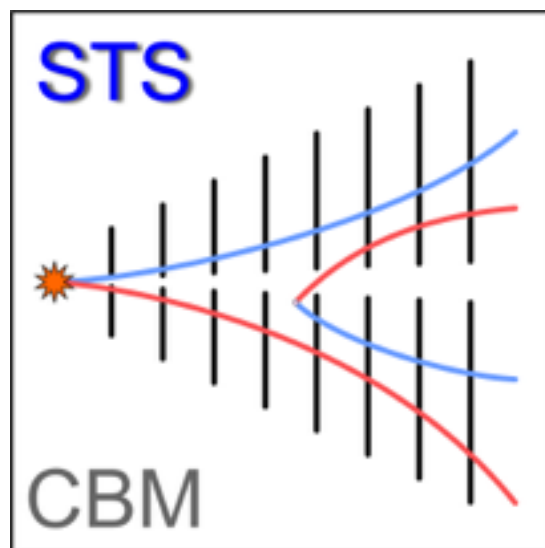
10^{11} central Ni+Ni events
15 GeV/nucleon, using TOF PID



5×10^6 central Au+Au events
10 GeV/nucleon, using TOF PID

Summary

- STS system concept has been presented
- Progress with prototyping and engineering
- Sensor prototypes delivered, radiation hardness is under investigation
- Current activity is module assembly and system integration
- Full-size module mockup has been produced
- System engineering: mechanical structure, mounting of electronics, cable routing. Close to completion.
- Feasibility for physics measurements demonstrated
- Production readiness in 2017



Institutions participating in STS

Germany

Darmstadt, Germany, GSI Helmholtz Center (GSI)

Karlsruhe, Germany, Karlsruhe Institute of Technology (KIT)

Tübingen, Germany, Eberhard Karls University (EKU)

Poland

Krakow, Poland, AGH University of Science and Technology (AGH)

Krakow, Poland, Jagiellonian University (JU)

Warsaw, Poland, Warsaw University of Technology (WUT)

Russia

Dubna, Russia, Joint Institute for Nuclear Research (JINR)

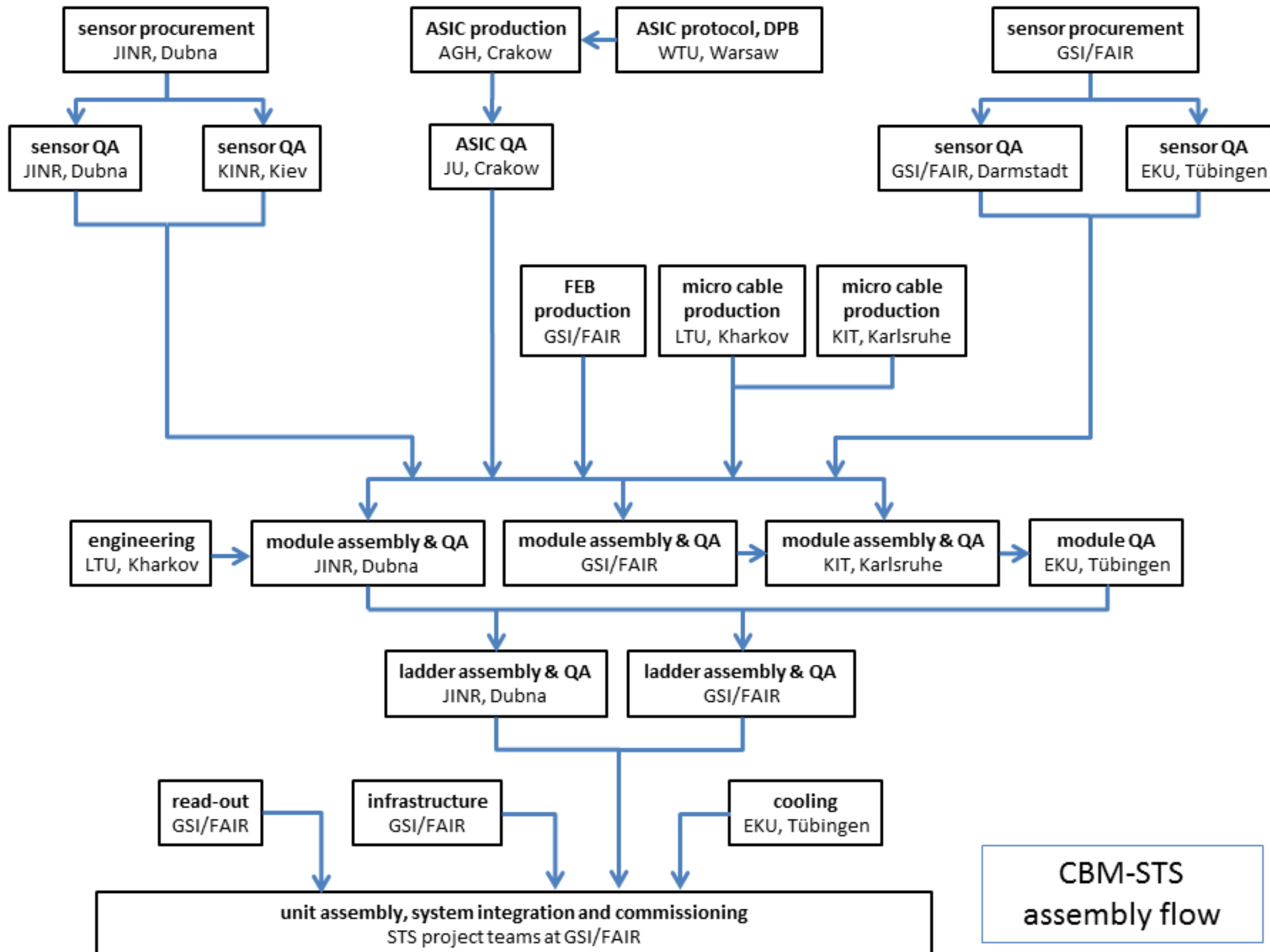
Moscow, Russia, Moscow State University (SINP-MSU)

Ukraine

*Kharkov, Ukraine, LED Technologies of Ukraine Ltd (LTU) * Partner*

Kiev, Ukraine, Kiev Institute for Nuclear Research (KINR)

CBM STS assembly flow



STS related presentations at DPG 2016

- **Mon, 14:45 HK 8.3** Grigory Kozlov
Time-based cluster and hit finding for the STS detector in the CBM experiment at FAIR
- **Mon, 15:00 HK 7.4** Evgeny Lavrik
Optical quality assurance procedures for the sensors of CBM STS Detector
- **Mon, 15:15 HK 7.5** Maksym Teklishyn
Quality assurance tests of the CBM Silicon Tracking System sensors with an infrared laser
- **Mon, 16:30 HK 14.1** Hanna Malygina
The detector response simulation for the CBM Silicon Tracking System as a tool for hit error estimation
- **Group talk Mon, 16:30 HK 15.1** Anton Lymanets
The Silicon Tracking System of the CBM Experiment at FAIR
- **Mon, 17:00 HK 15.2** Iaroslav Panasenko, Pavel Larionov
Quality assurance of the silicon microstrip sensors for the CBM experiment
- **Tue, 15:00 HK 21.4** Ievgeniia Momot
Radiation tolerance of microstrip sensors for the CBM Silicon Tracking System
- **Tue, 18:00 HK 29.7** Adrian Rodriguez Rodriguez
The CBM-STS front-end electronics
- **Wed, 18:30 HK 45.9** Carmen Simons, Daniel Soyk, and Robert Visinka
The workflow of CBM-STS silicon strip sensor module-assembly
- **Poster Wed, 18:30 HK 45.20** Evgeny Lavrik
Bi-Phase CO₂ cooling of the CBM STS detector
- **Poster Wed, 18:30 HK 45.63** Oleg Vasylyev, W. Niebur
Mechanical integration of the detector components for the CBM Silicon Tracking System
- **Thu, 17:45 HK 60.6** Jörg Lehnert, David Emschermann
The read-out chain of the CBM STS detector